Fabrication Notes:

- 1. All dimensions in inches unless noted otherwise.
- 2. All materials: laminates, resins, metallizations and soldermask to be compliant with RoHS and WEEE directives.
 3. Use 370 HR FR-4 or similar grade glass epoxy.
 4. Tg > 145 degrees C, glass transition temperature.
 5. TD > 350 degrees C, thermal decomposition.

- 6. Minimum flammibility rating UL94V-O, maximum dissipation factor 0.025.
- 7. Adjust prepreg for 0.032, +/- 0.003 finished thickness measured over soldermask. 8. Copper thickness 0.0014, (1 oz). 9. Hole size tolerance = +/- 0.003 unless noted otherwise.

- 10. Hole centers and pad centers to be concentric within 0.002.
- 11. Drill chart dimensions are finished hole sizes.
- 12. Finish immersion gold over nickel. No exposed bare copper permitted.
- 13. Solder mask over bare copper, LPI clas 2 gen. industrial registration +/- 0.004.

- 14. No coverage on solder pads permitted.
 15. Refer to soldermask gerbers for tenting of vias.
 16. White silkscreen legend over green soldermask both sides.
 17. Manufacturer icons not permitted on the silkscreen top layer.
 18. PCB serialization/panel placement ID on silkscreen bottom.
 19. Full electrical test against IPC-356A netlist.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,036mm		
4	Dielectric 1	FR-4	0,908mm	4,48	
5	Bottom Layer	Copper	0,036mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Pad Shape
	490	0,250mm	PTH	Round	Top Layer - Bottom Layer	Rounded
0	3	0,750mm	PTH	Round	Top Layer - Bottom Layer	Rounded
*	2	1,000mm	PTH	Round	Top Layer - Bottom Layer	Rounded
	495 Total					

